

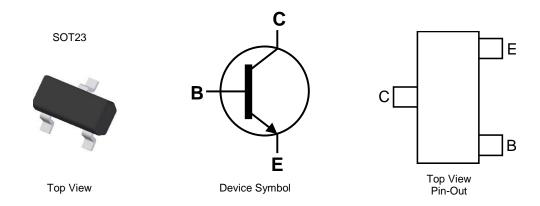
40V NPN SMALL SIGNAL TRANSISTOR IN SOT23

Features

- Epitaxial Planar Die Construction
- Complementary PNP Type: MMBT2907A
- Ideal for Low Power Amplification and Switching
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound;
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish; Solderable per MIL-STD-202, Method 208 (©3)
- Weight: 0.008 grams (Approximate)



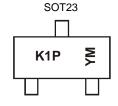
Ordering Information (Notes 4 & 5)

| Product | Status | Compliance | Marking | Reel Size (inches) | Tape Width (mm) | Quantity per Reel |
|----------------|--------|------------|---------|--------------------|-----------------|-------------------|
| MMBT2222A-7-F | Active | AEC-Q101 | K1P | 7 | 8 | 3,000 |
| MMBT2222A-13-F | Active | AEC-Q101 | K1P | 13 | 8 | 10,000 |
| MMBT2222AQ-7-F | Active | Automotive | K1P | 7 | 8 | 3,000 |

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen and Antimony free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive, AEC-Q101 and standard products are electrically and thermally the same, except where specified. For more information, please refer to http://www.diodes.com/product_compliance_definitions.html.
- 5. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



$$\begin{split} & \text{K1P} = \text{Product Type Marking Code} \\ & \text{YM} = \text{Date Code Marking} \\ & \text{Y or } \overline{\text{Y}} = \text{Year (ex: D} = 2016) \\ & \text{M or } \overline{\text{M}} = \text{Month (ex: 9} = \text{September)} \end{split}$$

Date Code Key

| Year | 201 | 5 2 | 016 | 2017 | 2018 | 2019 | 2020 | 202 | 1 2 | 022 | 2023 | 2024 |
|-------|-----|-----|-----|------|------|------|------|-----|-----|-----|------|------|
| Code | С | | D | Е | F | G | Н | 1 | | J | K | L |
| Month | Jan | Feb | Mar | Apr | May | Jun | Jul | Aug | Sep | Oct | Nov | Dec |
| Code | 1 | 2 | 3 | 4 | 5 | 6 | 7 | 8 | 9 | 0 | N | D |



Absolute Maximum Ratings (@TA = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Value | Unit |
|---------------------------|------------------|-------|------|
| Collector-Base Voltage | V _{CBO} | 75 | V |
| Collector-Emitter Voltage | V _{CEO} | 40 | V |
| Emitter-Base Voltage | V _{EBO} | 6.0 | V |
| Collector Current | Ic | 600 | mA |
| Peak Collector Current | I _{CM} | 800 | mA |
| Peak Base Current | I _{BM} | 200 | mA |

Thermal Characteristics (@TA = +25°C, unless otherwise specified.)

| Characteristic | | Symbol | Value | Unit | |
|--|-----------------|----------------|-------|------|--|
| Collector Power Dissipation | (Note 6) | 6 | 310 | mW | |
| Collector Power Dissipation | (Note 7) | P_{D} | 350 | | |
| Thermal Desistance Junction to Ambient | (Note 6) | D | 403 | °C/W | |
| Thermal Resistance, Junction to Ambient | (Note 7) | $R_{	heta JA}$ | 357 | C/VV | |
| Thermal Resistance, Junction to Leads (Note 8) | | $R_{	heta JL}$ | 350 | °C/W | |
| Operating and Storage Temperature Range | $T_{J,}T_{STG}$ | -55 to +150 | °C | | |

ESD Ratings (Note 9)

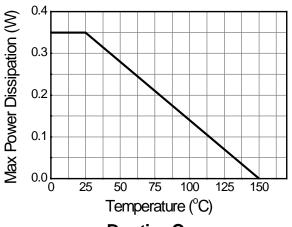
| Characteristic | Symbol | Value | Unit | JEDEC Class |
|--|---------|-------|------|-------------|
| Electrostatic Discharge - Human Body Model | ESD HBM | 4,000 | V | 3A |
| Electrostatic Discharge - Machine Model | ESD MM | 400 | V | С |

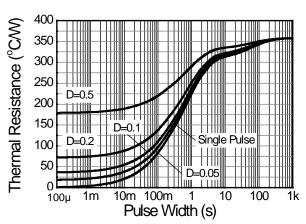
Notes:

- 6. For a device mounted on minimum recommended pad layout 1oz copper that is on a single-sided FR-4 PCB; device is measured under still air conditions whilst operating in a steady-state.
- 7. Same as Note 6, except the device is mounted on 15 mm x 15mm 1oz copper.
- 8. Thermal resistance from junction to solder-point (at the end of the leads). 9. Refer to JEDEC specification JESD22-A114 and JESD22-A115.



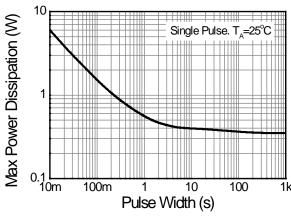
Thermal Characteristics and Derating Information





Derating Curve

Transient Thermal Impedance



Pulse Power Dissipation



Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Min | Max | Unit | Test Condition |
|---|----------------------|---|------------|----------|--|
| OFF CHARACTERISTICS | | | | | |
| Collector-Base Breakdown Voltage | BV _{CBO} | 75 | _ | V | $I_C = 100\mu A, I_E = 0$ |
| Collector-Emitter Breakdown Voltage (Note 10) | BV _{CEO} | 40 | _ | V | $I_C = 10 \text{mA}, I_B = 0$ |
| Emitter-Base Breakdown Voltage | BV _{EBO} | 6.0 | _ | V | $I_E = 100 \mu A, I_C = 0$ |
| Collector Cut-Off Current | I _{CBO} | _ | 10 | nΑ μΑ | V _{CB} = 60V, I _E = 0 V _{CB} = 60V, I _E = 0, T _A = +150°C |
| Collector Cut-Off Current | I _{CEX} | _ | 10 | nA | V _{CE} = 60V, V _{EB(OFF)} = 3.0V |
| Collector Cut-Off Current | I _{CEV} | _ | 10 | nA | $V_{CE} = 60V, V_{BE} = \pm 0.25V$ |
| Emitter Cut-Off Current | I _{EBO} | _ | 10 | nA | V _{EB} = 5.0V, I _C = 0 |
| Base Cut-Off Current | I _{BL} | _ | 20 | nA | V _{CE} = 60V, V _{EB(OFF)} = 3.0V |
| ON CHARACTERISTICS (Note 10) | | | • | | |
| DC Current Gain | h _{FE} | 35 50 75 100 40 50 35 | | _ | $\begin{split} &I_{C} = 100 \mu A, \ V_{CE} = 10 V \\ &I_{C} = 1.0 m A, \ V_{CE} = 10 V \\ &I_{C} = 10 m A, \ V_{CE} = 10 V \\ &I_{C} = 150 m A, \ V_{CE} = 10 V \\ &I_{C} = 500 m A, \ V_{CE} = 10 V \\ &I_{C} = 10 m A, \ V_{CE} = 10 V, \ T_{A} = -55 ^{\circ} C \\ &I_{C} = 150 m A, \ V_{CE} = 1.0 V \end{split}$ |
| Collector-Emitter Saturation Voltage | V _{CE(SAT)} | _ | 0.3 1.0 | V | I _C = 150mA, I _B = 15mA I _C = 500mA, I _B = 50mA |
| Base-Emitter Saturation Voltage | V _{BE(SAT)} | 0.6 | 1.2 2.0 | V | I _C = 150mA, I _B = 15mA I _C = 500mA, I _B = 50mA |
| SMALL SIGNAL CHARACTERISTICS | | | | l . | |
| Output Capacitance | C _{obo} | _ | 8 | pF | V _{CB} = 10V, f = 1.0MHz, I _E = 0 |
| Input Capacitance | C _{ibo} | | 25 | pF | V _{EB} = 0.5V, f = 1.0MHz, I _C = 0 |
| Current Gain-Bandwidth Product | f _T | 300 | _ | MHz | $V_{CE} = 20V, I_{C} = 20mA,$ f = 100MHz |
| Noise Figure | N _F | _ | 4.0 | dB | $V_{CE} = 10V, I_{C} = 100\mu A,$ $R_{S} = 1.0k\Omega, f = 1.0kHz$ |
| SWITCHING CHARACTERISTICS | | | | • | |
| Delay Time | t _D | | 10 | ns | $V_{CC} = 30V$, $I_C = 150mA$, $V_{BE(OFF)} = -0.5V$, $I_{B1} = 15mA$ |
| Rise Time | t _R | _ | 25 | ns | $V_{CC} = 3.0V$, $I_C = 150mA$, $I_{B1} = 15mA$, $V_{BE(OFF)} = 0.5V$ |
| Storage Time | ts | _ | 225 | ns | $V_{CC} = 30V$, $I_C = 150mA$, $I_{B1} = I_{B2} = 15mA$ |
| Fall Time | t _F | _ | 60 | ns | $V_{CC} = 30V$, $I_C = 150mA$, $I_{B1} = I_{B2} = 15mA$ |

Note: 10. Measured under pulsed conditions. Pulse width \leq 300 μ s. Duty cycle \leq 2%.



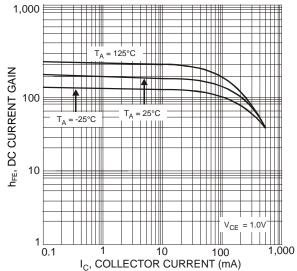
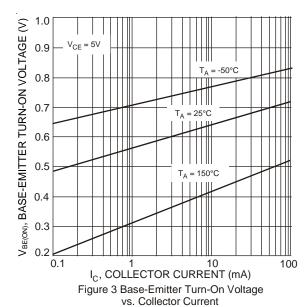


Figure 1 Typical DC Current Gain vs. Collector Current



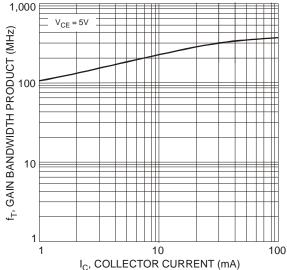


Figure 5 Typical Gain Bandwidth Product vs. Collector Current

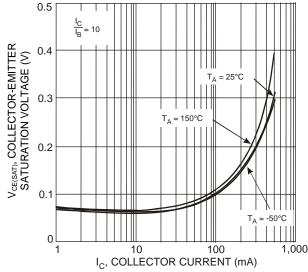


Figure 2 Typical Collector-Emitter Saturation Voltage vs. Collector Current

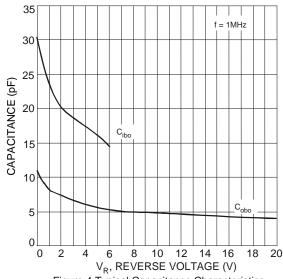


Figure 4 Typical Capacitance Characteristics

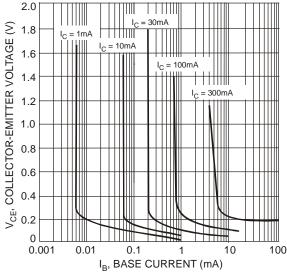


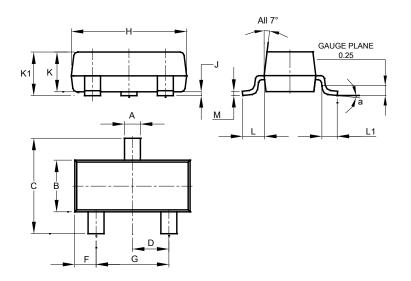
Figure 6 Typical Collector Saturation Region



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT23

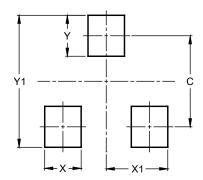


| SOT23 | | | | | | | |
|-------|----------------------|-------|-------|--|--|--|--|
| Dim | Min | Max | Тур | | | | |
| Α | 0.37 | 0.51 | 0.40 | | | | |
| В | 1.20 | 1.40 | 1.30 | | | | |
| С | 2.30 | 2.50 | 2.40 | | | | |
| D | 0.89 | 1.03 | 0.915 | | | | |
| F | 0.45 | 0.60 | 0.535 | | | | |
| G | 1.78 | 2.05 | 1.83 | | | | |
| Н | 2.80 | 3.00 | 2.90 | | | | |
| J | 0.013 | 0.10 | 0.05 | | | | |
| K | 0.890 | 1.00 | 0.975 | | | | |
| K1 | 0.903 | 1.10 | 1.025 | | | | |
| L | 0.45 | 0.61 | 0.55 | | | | |
| L1 | 0.25 | 0.55 | 0.40 | | | | |
| M | 0.085 | 0.150 | 0.110 | | | | |
| а | 0° | 8° | | | | | |
| All | All Dimensions in mm | | | | | | |

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

SOT23



| Dimensions | Value (in mm) |
|------------|---------------|
| C | 2.0 |
| Х | 0.8 |
| X1 | 1.35 |
| Y | 0.9 |
| Y1 | 2.9 |



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